



Docket No.: 005123 USA/Consilium/Consilium

PATENT/OFFICIAL

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Horne L. KOH

Serial No. 09/928,473

Filed: August 14, 2001

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Group Art Unit: 2812

Examiner:

For: TOOL SERVICES LAYER FOR PROVIDING TOOL SERVICE FUNCTIONS IN
CONJUNCTION WITH TOOL FUNCTIONS

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents
Washington, D.C. 20231

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

This submission does not constitute a representation that a search has been made or that no better art exists and does not constitute an admission or representation that any of the listed documents is material or constitutes prior art. If it should be determined that any of the listed documents does not constitute prior art under the United States law, Applicants reserve the right

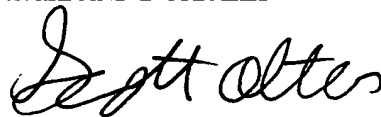
Serial No. 09/928,476

to present to the Office the relevant facts and law regarding the appropriate status of such document.

No certification or fee is believed to be required. However, the Commissioner is hereby authorized to charge any additional fees should any be required for this submission, or credit any overpayment to deposit account no. 08-0219.

Respectfully submitted,

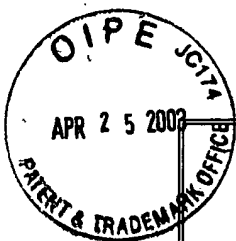
HALE AND DORR LLP

A handwritten signature in black ink, appearing to read "Scott M. Alter".

Scott M. Alter

Registration No. 32,879

1455 Pennsylvania Avenue, NW
Washington, DC 20004
TEL 202.942.8428 SMA/lrm
FAX 202.942.8484
Date: 4/25/03



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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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	3,229,198	01/11/66	Libby			09/28/62
	4,000,458	12/28/76	Miller et al.			08/21/75
	4,302,721	11/24/81	Urbanek et al.			05/15/79
	4,750,141	06/07/88	Judell et al.			11/26/85
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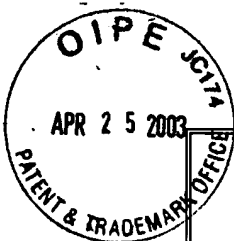
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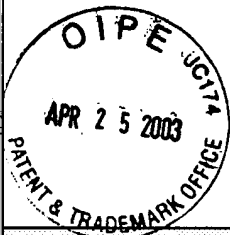
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	2002/0149359	10/17/02	Crouzen et al.			08/18/01
	6,479,902	11/12/02	Lopatin et al.			06/29/00
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	2002/0185658	12/12/02	Inoue et al.			06/14/01
	2002/0193902	12/19/02	Shanmugasundram et al.			06/18/02
	2002/0197745	12/26/02	Shanmugasundram et al.			08/31/01
	2002/0197934	12/26/02	Paik			11/30/01
	2002/0199082	12/26/02	Shanmugasundram et al.			06/18/02
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	61-66104	04/04/86	Japan			X	
	3-202710	09/04/91	Japan			X	
	8-23166	01/23/96	Japan			X	
	9-246547	09/19/97	Japan			X	
	WO 98/05066	02/05/98	WIPO			X	
	10-34522	02/10/98	Japan			X	
	0 869 652	10/07/98	Europe			X	
	WO 99/09371	02/25/99	WIPO			X	
	0 910 123	04/21/99	Europe			X	
	0 932 194	07/28/99	Europe			X	
	WO 00/00874	01/06/00	WIPO			X	
	2000-183001	06/30/00	Japan			X	

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						Yes	No
	1 071 128	01/24/01	Europe			X	
	WO 01/18623	03/15/01	WIPO			X	
	WO 01/25865	04/12/01	WIPO			X	
	434103	05/16/01	Taiwan			X	
	436383	05/28/01	Taiwan			X	
	455938	09/21/01	Taiwan			X	
	455976	09/21/01	Taiwan			X	
	2001-284299	10/12/01	Japan			X	
	2001-305108	10/31/01	Japan			X	
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<p style="text-align: center;">INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)</p> 	<p>ATTY. DOCKET NO. 005123 USA/Consilium/Consilium</p>	<p>SERIAL NO. 09/928,473</p>
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<p style="text-align: center;">OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</p>		
	<p>Boning, Duane S., William P. Moyne, Taber H. Smith, James Moyne, Ronald Telfeyan, Arnon Hurwitz, Scott Shellman, and John Taylor. October 1996. "Run by Run Control of Chemical-Mechanical Polishing." <i>IEEE Transactions on Components, Packaging, and Manufacturing Technology—Part C</i>, vol. 19, no. 4, pp. 307-314.</p>	
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Horne L. KOH

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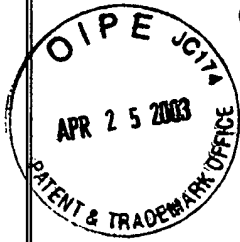
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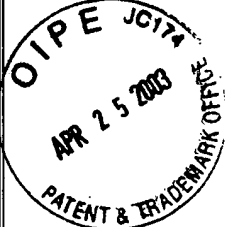
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